



Die-Bonder

5380

Bond System

Bondhead	Die-Bonding Bondforce from 5 to 500cN
Ultrasonic System	F&S Generator 67kHz (optional 120, 140)

Bonder Base

Axes

- Programmable linear Z-axis with 60mm stroke
- Programmable linear Y-axis with 20mm stroke
- Standard working height: 55 mm
- Manipulator in X and Y: 18x18 mm
- Equivalent to: 1: 7

Hardware

- Stepper motor driven Z-linear axis,
- Single-board PC, coin-guided teach-in,
- Internal hard disk, operation and menu-
- Guided via shuttle wheel with reset button

Software

- Programmable single Bonds
- Loop shapes can be stored

Control Manual, semil-automatic

Dimensions W x D x H – 63 x 58x 40 cm, weight approx. 30kg

Connections 100-230 VAC, 1 Phase, 50/60 Hz, max XXX VA
Ø 6mm standard-vuum tubing

Heater controller intergrated in the machine 0-250 °C

Die 53xx Series:

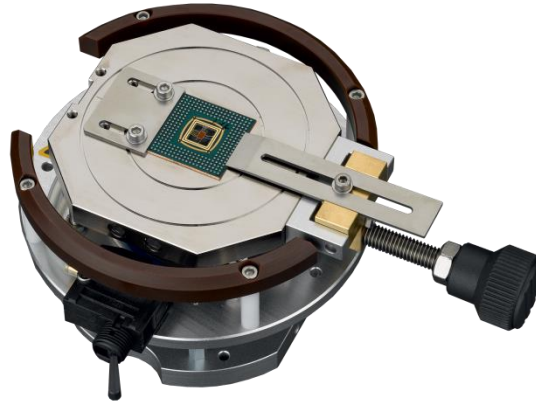
Our manual wirebonder 53XX BDA was already so far very versatile, because it can manufacture both Wedge and Ball bonds with simplest charge. Now a third function is added: the 53XX BDA can also bond DIE's now.

At the Bonder only minimum extensions are necessary in hard and soft-ware. Instead of the wire bond tool, an adapter is inserted into the Transducer directly, in order to take up standard tools for chip bonding, so called DIE Collets. On the market they are avail-able in different Shaft dia-meters, but they all fit into the three planned moun-ting holes. The chips are delivered in Wafflepacks, which are mounted be-side the normal substrate holder.

It is particularly attractive that the Bonder is changed in just a few short minutes to bonding. If the circuit with the chips placed comes thus hardened from the heater, the Bonder is ready again for the following wire bonding, the chip bond mechanism fits on all newer 53XX BDA wire-bonder. For the structure of sample or small numbers of items this is a highly welcome ex-tension, particularly since the bonding is not only economical, but takes place extremely sensitively and, for a manual Bonder, with high accuracy.

Workholder

Standard-Workholder
With mechanical clamping
Ø80mm



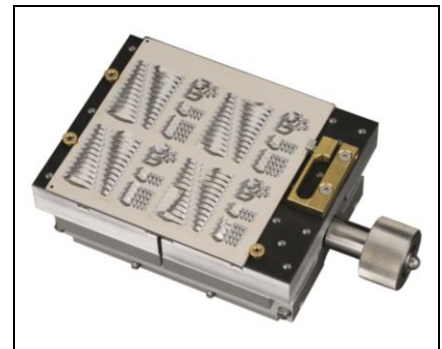
Optional:



workholder for parts up to 4x4"
with vacuum and mechanical
clamping



TO workholder with
mechanical clamping



4x4" workholder with
rubbered surface and
mechanical clamping

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